

SFF440-28

14849 Firestone Boulevard · La Mirada, CA 90638
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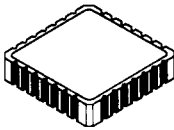
Designer's Data Sheet

FEATURES:

- Rugged construction with poly silicon gate
- Low RDS(on) and high transconductance
- Excellent high temperature stability
- Very fast switching speed
- Fast recovery and superior dv/dt performance
- Increased reverse energy capability
- Low input and transfer capacitance for easy paralleling
- Hermetically sealed surface mount package
- Low inductance leads
- TX, TXV and Space Level screening available
- Replaces: IRF440 Types

**8* AMP
 500 VOLTS
 0.88Ω
 N-CHANNEL
 POWER MOSFET**

28 PIN CLCC



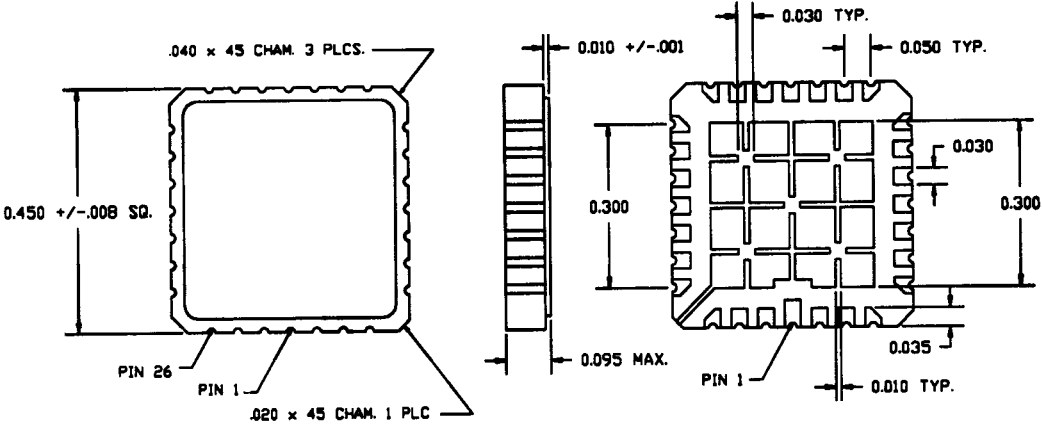
MAXIMUM RATINGS

CHARACTERISTIC	SYMBOL	VALUE	UNIT
Drain to Source Voltage	V _{DS}	500	Volts
Gate to Source Voltage	V _{GS}	±20	Volts
Continuous Drain Current	I _D	8	Amps
Operating and Storage Temperature	T _{OP} & T _{STG}	-55 to +150	°C
Thermal Resistance, Junction to Case	R _{θJC}	3.5	°C/W
Total Device Dissipation @ TC=25°C	P _D	36	Watts
Total Device Dissipation @ TC=80°C		27	

PACKAGE OUTLINE: 28 PIN CLCC

PIN OUT:
 SOURCE: 1, 15-28
 DRAIN: 5-11
 GATE: 2, 3, 13, 14

NOTE:
 All Drain/Source Pins must be connected on the PC Board in order to maximize current capability and minimize RDS(on)



Dimensions shown in drawings:
 Top view: 0.450 +/- .008 SQ. (overall width), .040 x 45 CHAM. 3 PLCS. (top chamfer), .020 x 45 CHAM. 1 PLC (bottom chamfer)
 Side view: 0.010 +/- .001 (lead height), 0.095 MAX. (lead length)
 Bottom view: 0.030 TYP. (lead pitch), 0.050 TYP. (lead width), 0.030 (lead width), 0.300 (package width), 0.035 (lead width), 0.010 TYP. (lead width)

* Rating based on size of chip. Device rating may vary depending on mounting and heatsink conditions. Consult SSDI Marketing department for thermal derating details.

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PRELIMINARY

SSDI**SOLID STATE DEVICES, INC**14849 Firestone Boulevard · La Mirada, CA 90638
Phone: (714) 670-SSDI (7734) · Fax: (714) 522-7424**ELECTRICAL CHARACTERISTICS @ T_J=25 °C (Unless Otherwise Specified)**

RATING		SYMBOL	MIN	TYP	MAX	UNIT
Drain to Source Breakdown Voltage (VGS=0 V, ID=250µA)		BVDSS	500	---	---	V
Drain to Source on State Resistance (VGS=10 V, ID=60% Rated ID)		RDS(on)	---	0.72	0.86	Ω
On State Drain Current (VDS > ID(on) X RDS(on) Max, VGS=10 V)		ID(on)	8	---	---	A
Gate Threshold Voltage (VDS=VGS, ID=250µA)		VGS(th)	2.0	---	4.0	V
Forward Transconductance (VDS ≥ 50V, IDS=60% rated ID)		gfs	4.9	7.4	---	S(Ω)
Zero Gate Voltage Drain Current (VDS=max rated voltage, VGS=0 V) (VDS=80% rated VDS, VGS=0 V, TA=125°C)		IDSS	---	---	250 1000	µA
Gate to Source Leakage Forward Gate to Source Leakage Reverse	At rated VGS	IGSS	---	---	100 -100	nA
Total Gate Charge Gate to Source Charge Gate to Drain Charge	VGS=10 Volts 80% rated VDS ID=8 A	Qg Qgs Qgd	---	42 6 22	63 10 32	nC
Turn on Delay Time Rise Time Turn Off Delay Time Fall Time	VDD=50% rated VDS ID= 8 A RG=9.1Ω RD=30Ω	td(on) tr td(off) tf	---	14 23 50 20	21 35 74 30	nsec
Diode Forward Voltage (IS=rated ID, VGS=0 V, TJ=25°C)		VSD	---	---	2.0	V
Diode Reverse Recovery Time Reverse Recovery Charge	TJ=25°C IF=rated ID di/dt=100 A/µsec	trr QRR	210 2	460 4,2	970 8.9	nsec µC
Input Capacitance Output Capacitance Reverse Transfer Capacitance	VGS=0 Volts VDS=25 Volts f= 1 MHz	Ciss Coss Crss	---	1300 180 45	---	pF

For thermal derating curves and other characteristic curves please contact SSDI Marketing Department.